

AMENDMENTS TO THE SPECIFICATION

Please delete the present title and replace it with the following title:

ELECTROPLATING PROCESS OF ELECTROPLATING AN ELECTRICALLY
CONDUCTIVE SUBSTRATE

Please amend the specification by amending the first paragraph as follows:

This is a Divisional of U.S. Patent Application No. 09/787,139, now U.S. Patent No. 7,230,188, which entered National Stage on March 14, 2001, and which is a §371 National Stage application of International Application No. PCT/JP99/05003, filed September 14, 1999, the contents of which are incorporated in their entirety herein by reference.